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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	8272
Number of Logic Elements/Cells	74448
Total RAM Bits	6045696
Number of I/O	996
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1704-BBGA, FCBGA
Supplier Device Package	1704-FCBGA (42.5x42.5)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp70-7ff1704c

Serializer

The serializer multiplies the reference frequency provided on REFCLK by 20. The multiplication of the clock is achieved by using an embedded PLL.

Data is converted from parallel to serial format and transmitted on the TXP and TXN differential outputs. The electrical connection of TXP and TXN can be interchanged through configuration. This option can be controlled by an input (TXPOLARITY) at the FPGA transmitter interface.

Deserializer

The serial transceiver input is locked to the input data stream through Clock and Data Recovery (CDR), a built-in feature of the RocketIO transceiver. CDR keys off the rising and falling edges of incoming data and derives a clock that is representative of the incoming data rate.

The derived clock, RXRECCLK, is generated and locked to as long as it remains within the specified component range. This clock is presented to the FPGA fabric at $^1/_{20}$ the incoming data rate.

A sufficient number of transitions must be present in the data stream for CDR to work properly. CDR requires approximately 5,000 transitions upon power-up to guarantee locking to the incoming data rate. Once lock is achieved, up to 75 missing transitions can be tolerated before lock to the incoming data stream is lost. The CDR circuit is guaranteed to work with 8B/10B encoding.

Another feature of CDR is its ability to accept an external precision reference clock, REFCLK, which either acts to clock incoming data or to assist in synchronizing the derived RXRECCLK.

For further clarity, the TXUSRCLK is used to clock data from the FPGA fabric to the TX FIFO. The FIFO depth accounts for the slight phase difference between these two clocks. If the clocks are locked in frequency, then the FIFO acts much like a pass-through buffer.

The receiver can be configured to reverse the RXP and RXN inputs. This can be useful in the event that printed circuit board traces have been reversed.

Receiver Termination

On-chip termination is provided at the receiver, eliminating the need for external termination. The receiver includes programmable on-chip termination circuitry for 50Ω (default) or 75Ω impedance, as shown in Figure 11.

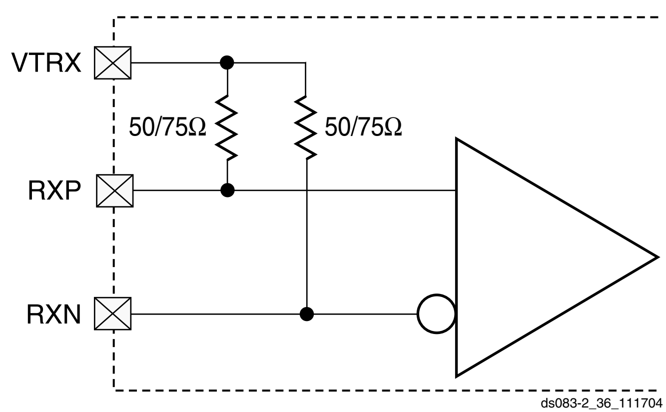


Figure 11: **RocketIO Receive Termination**

PCS

Fabric Data Interface

Internally, the PCS operates in 2-byte mode (16/20 bits). The FPGA fabric interface can either be 1, 2, or 4 bytes wide. When accompanied by the predefined modes of the PMA, the user thus has a large combination of protocols and data rates from which to choose.

USRCLK2 clocks data on the fabric side, while USRCLK clocks data on the PCS side. This creates distinct USRCLK/USRCLK2 frequency ratios for different combinations of fabric and internal data widths. Table 5 summarizes the USRCLK2 to USRCLK ratios for the three fabric data widths.

No fixed phase relationship is assumed between REFCLK, RXRECCLK, and/or any other clock that is not tied to either of these clocks. When RXUSRCLK and RXUSRCLK2 have different frequencies, each edge of the slower clock is aligned to a falling edge of the faster clock. The same relationships apply to TXUSRCLK and TXUSRCLK2.

Table 3: **DC Characteristics Over Recommended Operating Conditions**

Symbol	Description	Virtex-II Pro X			Virtex-II Pro			Units
		Min	Typ	Max	Min	Typ	Max	
V_{DRINT}	Data retention V_{CCINT} voltage (below which configuration data might be lost)	1.25			1.25			V
V_{DRI}	Data retention V_{CCAUX} voltage (below which configuration data might be lost)	2.0			2.0			V
I_{REF}	V_{REF} current per pin			10			10	µA
I_L	Input or output leakage current per pin (sample-tested)			10			10	µA
C_{IN}	Input capacitance (sample-tested)			10			10	pF
I_{RPU}	Pad pull-up (when selected) @ V_{in} = 0V, V_{CCO} = 2.5V (sample tested)			150			150	µA
I_{RPD}	Pad pull-down (when selected) @ V_{in} = 2.5V (sample-tested)			150			150	µA
I_{BATT}(1)	Battery supply current	Note (2)			Note (2)			nA
$I_{CCAUXTX}$	Operating AVCCAUXTX supply current		115			60	105	mA
$I_{CCAUXRX}$	Operating AVCCAUXRX supply current		85			35	75	mA
I_{TTX}	Operating I_{TTX} supply current when transmitter is AC-coupled		55			30		mA
	Operating I_{TTX} supply current when transmitter is DC-coupled	N/A	N/A	N/A		15		mA
I_{TRX}	Operating I_{TRX} supply current when receiver is AC-coupled		15			0		mA
	Operating I_{TRX} supply current when receiver is DC-coupled	N/A	N/A	N/A		15		
P_{CPU}	Power dissipation of PowerPC™ 405 processor block		0.9			0.9		mW/ MHz
P_{RXTX}(3)	Power dissipation of MGT @ 1.25 Gb/s per channel	N/A	N/A	N/A		230		mW
	Power dissipation of MGT @ 2.5 Gb/s per channel		290			310		mW
	Power dissipation of MGT @ 3.125 Gb/s per channel		310			350		mW
	Power dissipation of MGT @ 4.25 Gb/s per channel		450		N/A	N/A	N/A	mW
	Power dissipation of MGT @ 6.25 Gb/s per channel		525		N/A	N/A	N/A	mW

Notes:

1. Characterized, not tested.
2. Battery supply current (I_{BATT}):

	Device Unpowered	Device Powered	Units
25°C:	< 50	< 10	nA
85°C:	N/A	< 10	nA

3. Total dissipation of fully operational PMA and PCS combined. This power is the average power supply dissipation per MGT. The averaging was done by simultaneously turning on all eight transceivers and dividing the total power supply dissipation by eight.

Table 38: **IOB Output Switching Characteristics Standard Adjustments *(Continued)***

Description	IOSTANDARD Attribute	Timing Parameter	Speed Grade			Units
			-7	-6	-5	
HSTL, Class II	HSTL_II	T_{OHSTL_II}	0.30	0.35	0.38	ns
HSTL, Class III	HSTL_III	T_{OHSTL_IIII}	0.31	0.35	0.39	ns
HSTL, Class IV	HSTL_IV	T_{OHSTL_IV}	0.15	0.17	0.19	ns
HSTL, Class I, 1.8V	HSTL_I_18	$T_{OHSTL\_I\_18}$	0.56	0.64	0.70	ns
HSTL, Class II, 1.8V	HSTL_II_18	$T_{OHSTL\_II\_18}$	0.30	0.35	0.38	ns
HSTL, Class III, 1.8V	HSTL_III_18	$T_{OHSTL\_IIII\_18}$	0.36	0.41	0.45	ns
HSTL, Class IV, 1.8V	HSTL_IV_18	$T_{OHSTL\_IV\_18}$	0.19	0.22	0.24	ns
SSTL (Stub Series Terminated Logic), Class I, 1.8V	SSTL18_I	$T_{OSSTL18\_I}$	0.80	0.92	1.01	ns
SSTL, Class II, 1.8V	SSTL18_II	$T_{OSSTL18\_II}$	0.45	0.51	0.56	ns
SSTL, Class I, 2.5V	SSTL2_I	T_{OSSTL2_I}	0.63	0.72	0.79	ns
SSTL, Class II, 2.5V	SSTL2_II	T_{OSSTL2_II}	0.22	0.25	0.27	ns
LVDCI (Low-Voltage Digitally Controlled Impedance), 3.3V	LVDCI_33	T_{OLVDCI_33}	0.72	0.83	0.91	ns
LVDCI, 2.5V	LVDCI_25	T_{OLVDCI_25}	0.56	0.64	0.71	ns
LVDCI, 1.8V	LVDCI_18	T_{OLVDCI_18}	0.65	0.75	0.82	ns
LVDCI, 1.5V	LVDCI_15	T_{OLVDCI_15}	1.00	1.15	1.26	ns
LVDCI, 2.5V, Half-Impedance	LVDCI_DV2_25	$T_{OLVDCI\_DV2\_25}$	0.06	0.07	0.08	ns
LVDCI, 1.8V, Half-Impedance	LVDCI_DV2_18	$T_{OLVDCI\_DV2\_18}$	0.30	0.34	0.38	ns
LVDCI, 1.5V, Half-Impedance	LVDCI_DV2_15	$T_{OLVDCI\_DV2\_15}$	0.60	0.69	0.76	ns
HSLVDCI (High-Speed Low-Voltage DCI), 1.5V	HSLVDCI_15	$T_{OHSLVDCI\_15}$	1.00	1.15	1.26	ns
HSLVDCI, 1.8V	HSLVDCI_18	$T_{OHSLVDCI\_18}$	0.65	0.75	0.82	ns
HSLVDCI, 2.5V	HSLVDCI_25	$T_{OHSLVDCI\_25}$	0.56	0.64	0.71	ns
HSLVDCI, 3.3V	HSLVDCI_33	$T_{OHSLVDCI\_33}$	0.72	0.83	0.91	ns
GTL (Gunning Transceiver Logic) with DCI	GTL_DCI	T_{OGTL_DCI}	1.21	1.39	1.53	ns
GTL Plus with DCI	GTLP_DCI	T_{OGTLP_DCI}	0.05	0.06	0.07	ns
HSTL (High-Speed Transceiver Logic), Class I, with DCI	HSTL_I_DCI	$T_{OHSTL\_I\_DCI}$	0.55	0.63	0.69	ns
HSTL, Class II, with DCI	HSTL_II_DCI	$T_{OHSTL\_II\_DCI}$	0.47	0.54	0.60	ns
HSTL, Class III, with DCI	HSTL_III_DCI	$T_{OHSTL\_III\_DCI}$	0.31	0.36	0.40	ns
HSTL, Class IV, with DCI	HSTL_IV_DCI	$T_{OHSTL\_IV\_DCI}$	1.81	2.08	2.29	ns
HSTL, Class I, 1.8V, with DCI	HSTL_I_DCI_18	$T_{OHSTL\_I\_DCI\_18}$	0.55	0.63	0.70	ns
HSTL, Class II, 1.8V, with DCI	HSTL_II_DCI_18	$T_{OHSTL\_II\_DCI\_18}$	0.24	0.28	0.31	ns
HSTL, Class III, 1.8V, with DCI	HSTL_III_DCI_18	$T_{OHSTL\_III\_DCI\_18}$	0.35	0.40	0.44	ns
HSTL, Class IV, 1.8V, with DCI	HSTL_IV_DCI_18	$T_{OHSTL\_IV\_DCI\_18}$	1.48	1.70	1.87	ns
SSTL (Stub Series Terminated Logic), Class I, 1.8V, with DCI	SSTL18_I_DCI	$T_{OSSTL18\_I\_DCI}$	0.54	0.62	0.68	ns
SSTL, Class II, 1.8V, with DCI	SSTL18_II_DCI	$T_{OSSTL18\_II\_DCI}$	0.24	0.28	0.31	ns
SSTL, Class I, 2.5V, with DCI	SSTL2_I_DCI	$T_{OSSTL2\_I\_DCI}$	0.48	0.56	0.61	ns
SSTL, Class II, 2.5V, with DCI	SSTL2_II_DCI	$T_{OSSTL2\_II\_DCI}$	0.48	0.56	0.61	ns

Global Clock Input to Output Delay for LVCMOS25, 12 mA, Fast Slew Rate, *Without* DCM

Table 54: **Global Clock Input to Output Delay for LVCMOS25, 12 mA, Fast Slew Rate, *Without* DCM**

			Speed Grade			
Description	**Symbol**	**Device**	**-7**	**-6**	**-5**	**Units**
LVCMOS25 Global Clock Input to Output Delay using Output Flip-flop, 12 mA, Fast Slew Rate, *without* DCM. For data *output* with different standards, adjust the delays with the values shown in IOB Output Switching Characteristics Standard Adjustments, page 28.						
Global Clock and OFF without DCM	T_{ICKOF}	XC2VP2	3.19	3.52	3.82	ns
		XC2VP4	3.39	3.91	4.27	ns
		XC2VP7	3.59	4.00	4.36	ns
		XC2VP20	3.62	4.08	4.46	ns
		XC2VPX20	3.62	4.08	4.46	ns
		XC2VP30	3.73	4.12	4.50	ns
		XC2VP40	3.89	4.28	4.67	ns
		XC2VP50	4.00	4.43	4.84	ns
		XC2VP70	4.38	4.87	5.33	ns
		XC2VPX70	4.38	4.87	5.33	ns
		XC2VP100	N/A	5.32	5.82	ns

Notes:

1. Listed above are representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible IOB and CLB flip-flops are clocked by the global clock net.
2. Output timing is measured at 50% V_{CC} threshold with test setup shown in Figure 6. For other I/O standards, see Table 40.
3. DCM output jitter is already included in the timing calculation.

Virtex-II Pro Receiver Data-Valid Window (R_X)

R_X is the required minimum aggregate valid data period for a source-synchronous data bus at the pins of the device and is calculated as follows:

R_X = [TSAMP(1) + TCKSKEW(2) + TPKGSKEW(3)]

Notes:

1. This parameter indicates the total sampling error of Virtex-II Pro DDR input registers across voltage, temperature, and process. The characterization methodology uses the DCM to capture the DDR input registers' edges of operation. These measurements include:
   - CLK0 and CLK180 DCM jitter in a quiet system
   - Worst-case duty-cycle distortion
   - DCM accuracy (phase offset)
   - DCM phase shift resolution.

   These measurements do not include package or clock tree skew.
2. This value represents the worst-case clock-tree skew observable between sequential I/O elements. Significantly less clock-tree skew exists for I/O registers that are close to each other and fed by the same or adjacent clock-tree branches. Use the Xilinx FPGA_Editor and Timing Analyzer tools to evaluate clock skew specific to your application.
3. These values represent the worst-case skew between any two balls of the package: shortest flight time to longest flight time from Pad to Ball.

Revision History

This section records the change history for this module of the data sheet.

Date	Version	Revision
01/31/02	1.0	Initial Xilinx release.
06/17/02	2.0	• Added new Virtex-II Pro family members. • Added timing parameters from speedsfile **v1.62**. • Added Table 46, Pipelined Multiplier Switching Characteristics. • Added 3.3V-vs-2.5V table entries for some parameters.
09/03/02	2.1	• Added Source-Synchronous Switching Characteristics section. • Added absolute max ratings for 3.3V-vs-2.5V parameters in Table 1. • Added recommended operating conditions for V_{IN} and RocketIO footnote to Table 2. • Updated SSTL2 values in Table 6. Added SSTL18 values: Table 6, Table 39, Table 32. [Table 32 removed in v2.8.] • Added Table 10, which contains LVPECL DC specifications.
09/27/02	2.2	Added section General Power Supply Requirements.
11/20/02	2.3	Updated parametric information in: • Table 1: Increase Absolute Max Rating for V_{CCO}, V_{REF}, V_{IN}, and V_{TS} from 3.6V to 3.75V. Delete cautionary footnotes related to voltage overshoot/undershoot. • Table 2: Delete V_{CCO} specifications for 2.5V and below operation. Delete footnote referencing special information for 3.3V operation. Add footnote for PCI/PCI-X. • Table 3: Add I_{BATT}. Delete I_L specifications for 2.5V and below operation. • Table 4: Add Typical Quiescent Supply Currents for XC2VP4 and XC2VP7 only • Table 6: Correct I_{OL} and I_{OH} for SSTL2 I. Add rows for LVTTL, LVCMOS33, and PCI-X. Correct max V_{IH} from V_{CCO} to 3.6V. • Table 7: Correct Min/Max V_{OD}, V_{OCM}, and V_{ICM} • Table 10: Reformat LVPECL DC Specifications to match Virtex-II data sheet format • Table 12: Correct parameter name from Differential Output Voltage to Single-Ended Output Voltage Swing. • Table 16: Add CPMC405CLOCK max frequencies • Table 27: Add footnote regarding serial data rate limitation in -5 part. • Table 39: Add rows for LVTTL, LVCMOS33, and PCI-X. • Table 32: Add LVTTL, LVCMOS33, and PCI-X. Correct all capacitive load values (except PCI/PCI-X) to 0 pF. [Table 32 removed in v2.8.] • Table 51: Correct CCLK max frequencies
11/25/02	2.4	Table 1: Correct lower limit of voltage range of V_{IN} and V_{TS} from –0.3V to –0.5V for 3.3V.

Table 5: **FG256/FGG256 — XC2VP2 and XC2VP4**

Bank	Pin Description	Pin Number
3	IO_L05P_3	L13
3	IO_L03N_3/VREF_3	L12
3	IO_L03P_3	M13
3	IO_L02N_3	M16
3	IO_L02P_3	N16
3	IO_L01N_3/VRP_3	M15
3	IO_L01P_3/VRN_3	M14
4	IO_L01N_4/BUSY/DOUT(1)	P15
4	IO_L01P_4/INIT_B	P14
4	IO_L02N_4/D0/DIN(1)	R14
4	IO_L02P_4/D1	P13
4	IO_L03N_4/D2	T15
4	IO_L03P_4/D3	T14
4	IO_L06N_4/VRP_4	N12
4	IO_L06P_4/VRN_4	P12
4	IO_L07P_4/VREF_4	N11
4	IO_L09N_4	M11
4	IO_L09P_4/VREF_4	M10
4	IO_L69N_4	N10
4	IO_L69P_4/VREF_4	P10
4	IO_L74N_4/GCLK3S	N9
4	IO_L74P_4/GCLK2P	P9
4	IO_L75N_4/GCLK1S	R9
4	IO_L75P_4/GCLK0P	T9
5	IO_L75N_5/GCLK7S	T8
5	IO_L75P_5/GCLK6P	R8
5	IO_L74N_5/GCLK5S	P8
5	IO_L74P_5/GCLK4P	N8
5	IO_L69N_5/VREF_5	P7
5	IO_L69P_5	N7
5	IO_L09N_5/VREF_5	M7
5	IO_L09P_5	M6
5	IO_L07N_5/VREF_5	N6

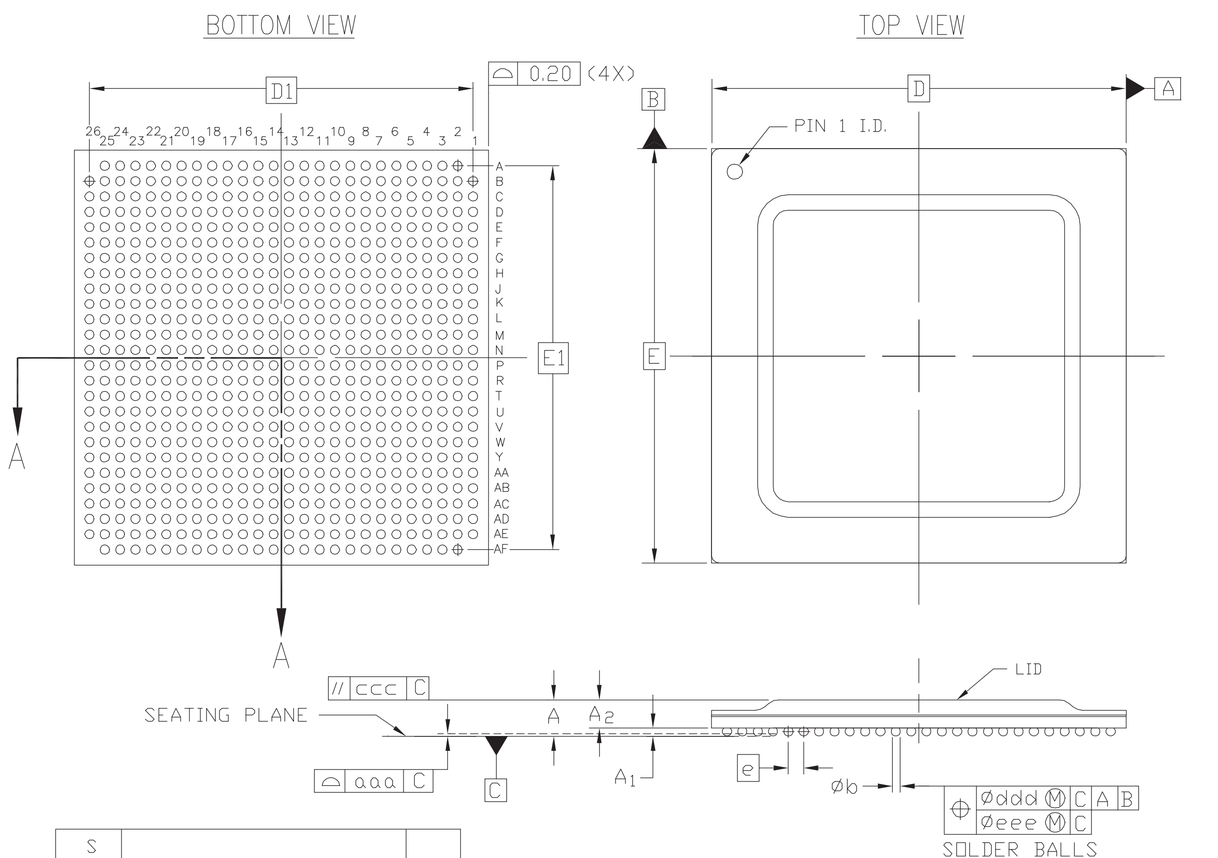
Table 6: **FG456/FGG456 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
2	IO_L56N_2	J21	NC		
2	IO_L56P_2	J22	NC		
2	IO_L58N_2/VREF_2	J18	NC		
2	IO_L58P_2	K18	NC		
2	IO_L60N_2	K19	NC		
2	IO_L60P_2	K20	NC		
2	IO_L85N_2	K21			
2	IO_L85P_2	K22			
2	IO_L86N_2	K17			
2	IO_L86P_2	L17			
2	IO_L88N_2/VREF_2	L18			
2	IO_L88P_2	L19			
2	IO_L90N_2	L20			
2	IO_L90P_2	L21			
3	IO_L90N_3	M21			
3	IO_L90P_3	M20			
3	IO_L89N_3	M19			
3	IO_L89P_3	M18			
3	IO_L87N_3/VREF_3	M17			
3	IO_L87P_3	N17			
3	IO_L85N_3	N22			
3	IO_L85P_3	N21			
3	IO_L60N_3	N20	NC		
3	IO_L60P_3	N19	NC		
3	IO_L59N_3	N18	NC		
3	IO_L59P_3	P18	NC		
3	IO_L57N_3/VREF_3	P22	NC		
3	IO_L57P_3	P21	NC		
3	IO_L55N_3	P20	NC		
3	IO_L55P_3	P19	NC		
3	IO_L54N_3	P17	NC		
3	IO_L54P_3	R18	NC		
3	IO_L53N_3	R22	NC		
3	IO_L53P_3	R21	NC		
3	IO_L51N_3/VREF_3	R20	NC		
3	IO_L51P_3	R19	NC		

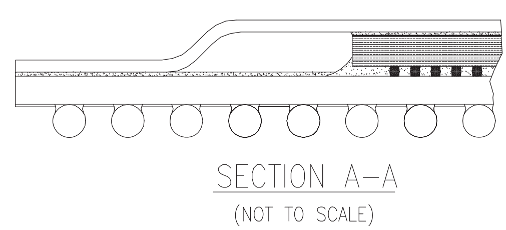
Table 8: **FF672 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
7	VCCO_7	L18			
7	VCCO_7	M18			
7	VCCO_7	N18			
N/A	CCLK	W7			
N/A	PROG_B	D22			
N/A	DONE	AB6			
N/A	M0	AC22			
N/A	M1	W20			
N/A	M2	AB21			
N/A	TCK	G8			
N/A	TDI	H20			
N/A	TDO	H7			
N/A	TMS	F7			
N/A	PWRDWN_B	AC5			
N/A	HSWAP_EN	E21			
N/A	RSVD	D5			
N/A	VBATT	E6			
N/A	DXP	F20			
N/A	DXN	G19			
N/A	AVCCAUXTX7	B11			
N/A	VTTXPAD7	B12			
N/A	TXNPAD7	A12			
N/A	TXPPAD7	A11			
N/A	GNDA7	C11			
N/A	RXPPAD7	A10			
N/A	RXNPAD7	A9			
N/A	VTRXPAD7	B10			
N/A	AVCCAUXRX7	B9			
N/A	AVCCAUXTX9	B6	NC	NC	
N/A	VTTXPAD9	B7	NC	NC	
N/A	TXNPAD9	A7	NC	NC	
N/A	TXPPAD9	A6	NC	NC	
N/A	GNDA9	C5	NC	NC	
N/A	RXPPAD9	A5	NC	NC	
N/A	RXNPAD9	A4	NC	NC	
N/A	VTRXPAD9	B5	NC	NC	

FF672 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch)



SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	~	2.45	2.65	
A_1	0.40	0.50	0.60	
A_2	~	~	2.15	
D/E	27.00 BASIC			
D_1/E_1	25.00 REF			
e	1.00 BASIC			
Øb	0.50	0.60	0.70	
aaa	~	~	0.20	
ccc	~	~	0.35	
ddd	~	~	0.30	
eee	~	~	0.10	
M	26			2



NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M–1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS–034–AAL–1 (DEPOPULATED)

Figure 4: **FF672 Flip-Chip Fine-Pitch BGA Package Specifications**

FF896 Flip-Chip Fine-Pitch BGA Package

As shown in Table 9, XC2VP7, XC2VP20, and XC2VP30 Virtex-II Pro devices are available in the FF896 flip-chip fine-pitch BGA package. Pins in each of these devices are the same, except for differences shown in the "No Connects" column. Following this table are the FF896 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch).

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
0	IO_L53_0/No_Pair		A21	NC		
0	IO_L54N_0		H18	NC		
0	IO_L54P_0		G18	NC		
0	IO_L56N_0		C21	NC		
0	IO_L56P_0		C20	NC		
0	IO_L57N_0		J17	NC		
0	IO_L57P_0/VREF_0		H17	NC		
0	IO_L67N_0		E17			
0	IO_L67P_0		D17			
0	IO_L68N_0		D18			
0	IO_L68P_0		C18			
0	IO_L69N_0		J16			
0	IO_L69P_0/VREF_0		H16			
0	IO_L73N_0		E16			
0	IO_L73P_0		D16			
0	IO_L74N_0/GCLK7P		C16			
0	IO_L74P_0/GCLK6S		B16			
0	IO_L75N_0/GCLK5P	BREFCLKN	G16			
0	IO_L75P_0/GCLK4S	BREFCLKP	F16			
1	IO_L75N_1/GCLK3P		F15			
1	IO_L75P_1/GCLK2S		G15			
1	IO_L74N_1/GCLK1P		B15			
1	IO_L74P_1/GCLK0S		C15			
1	IO_L73N_1		D15			
1	IO_L73P_1		E15			
1	IO_L69N_1/VREF_1		H15			
1	IO_L69P_1		J15			
1	IO_L68N_1		C13			
1	IO_L68P_1		D13			
1	IO_L67N_1		D14			
1	IO_L67P_1		E14			
1	IO_L57N_1/VREF_1		H14	NC		
1	IO_L57P_1		J14	NC		
1	IO_L56N_1		C11	NC		
1	IO_L56P_1		C10	NC		

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
5	IO_L48N_5		AH20	NC		
5	IO_L48P_5		AH21	NC		
5	IO_L47N_5		AE19	NC		
5	IO_L47P_5		AE20	NC		
5	IO_L46N_5		AD18	NC		
5	IO_L46P_5		AC18	NC		
5	IO_L45N_5/VREF_5		AJ22			
5	IO_L45P_5		AH22			
5	IO_L44N_5		AE21			
5	IO_L44P_5		AE22			
5	IO_L43N_5		AD19			
5	IO_L43P_5		AC19			
5	IO_L39N_5		AG21			
5	IO_L39P_5		AF21			
5	IO_L38N_5		AF22			
5	IO_L38P_5		AF23			
5	IO_L37N_5		AD20			
5	IO_L37P_5		AC20			
5	IO_L09N_5/VREF_5		AK23			
5	IO_L09P_5		AJ23			
5	IO_L08N_5		AE23			
5	IO_L08P_5		AE24			
5	IO_L07N_5/VREF_5		AD21			
5	IO_L07P_5		AC21			
5	IO_L06N_5/VRP_5		AH23			
5	IO_L06P_5/VRN_5		AG23			
5	IO_L05_5/No_Pair		AD23			
5	IO_L03N_5/D4		AH24			
5	IO_L03P_5/D5		AG24			
5	IO_L02N_5/D6		AD22			
5	IO_L02P_5/D7		AC22			
5	IO_L01N_5/RDWR_B		AF24			
5	IO_L01P_5/CS_B		AG25			
6	IO_L01P_6/VRN_6		AK28			
6	IO_L01N_6/VRP_6		AJ28			

FF1152 Flip-Chip Fine-Pitch BGA Package

As shown in Table 10, XC2VP20, XC2VP30, XC2VP40, and XC2VP50 Virtex-II Pro devices are available in the FF1152 flip-chip fine-pitch BGA package. Pins in each of these devices are the same, except for the differences shown in the No Connect column. Following this table are the FF1152 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch).

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
0	IO_L01N_0/VRP_0	E29				
0	IO_L01P_0/VRN_0	E28				
0	IO_L02N_0	H26				
0	IO_L02P_0	G26				
0	IO_L03N_0	H25				
0	IO_L03P_0/VREF_0	G25				
0	IO_L05_0/No_Pair	J25				
0	IO_L06N_0	K24				
0	IO_L06P_0	J24				
0	IO_L07N_0	F26				
0	IO_L07P_0	E26				
0	IO_L08N_0	D30				
0	IO_L08P_0	D29				
0	IO_L09N_0	K23				
0	IO_L09P_0/VREF_0	J23				
0	IO_L19N_0	F24	NC	NC		
0	IO_L19P_0	E24	NC	NC		
0	IO_L20N_0	D28	NC	NC		
0	IO_L20P_0	C28	NC	NC		
0	IO_L21N_0	H24	NC	NC		
0	IO_L21P_0	G24	NC	NC		
0	IO_L25N_0	G23	NC	NC		
0	IO_L25P_0	F23	NC	NC		
0	IO_L26N_0	E27	NC	NC		
0	IO_L26P_0	D27	NC	NC		
0	IO_L27N_0	K22	NC	NC		
0	IO_L27P_0/VREF_0	J22	NC	NC		
0	IO_L37N_0	H22				
0	IO_L37P_0	G22				
0	IO_L38N_0	D26				
0	IO_L38P_0	C26				
0	IO_L39N_0	K21				
0	IO_L39P_0	J21				
0	IO_L43N_0	F22				

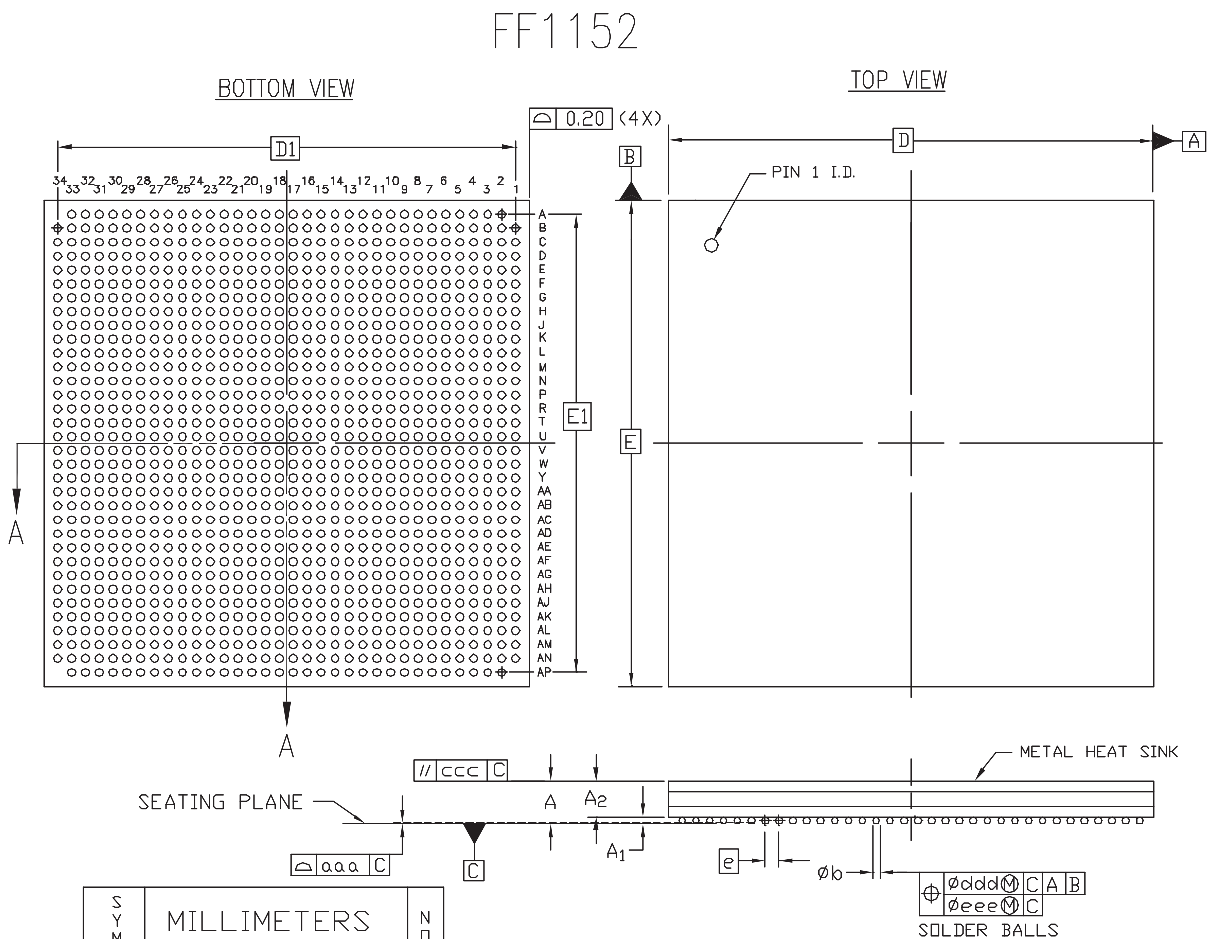
Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
6	IO_L01P_6/VRN_6	AJ30				
6	IO_L01N_6/VRP_6	AJ31				
6	IO_L02P_6	AJ27				
6	IO_L02N_6	AJ28				
6	IO_L03P_6	AK31				
6	IO_L03N_6/VREF_6	AK32				
6	IO_L04P_6	AH29				
6	IO_L04N_6	AH30				
6	IO_L05P_6	AH27				
6	IO_L05N_6	AG28				
6	IO_L06P_6	AL33				
6	IO_L06N_6	AL34				
6	IO_L15P_6	AG29	NC			
6	IO_L15N_6/VREF_6	AG30	NC			
6	IO_L16P_6	AK33	NC			
6	IO_L16N_6	AK34	NC			
6	IO_L17P_6	AF27	NC			
6	IO_L17N_6	AF28	NC			
6	IO_L18P_6	AJ33	NC			
6	IO_L18N_6	AJ34	NC			
6	IO_L19P_6	AH31	NC			
6	IO_L19N_6	AH32	NC			
6	IO_L20P_6	AD25	NC			
6	IO_L20N_6	AD26	NC			
6	IO_L21P_6	AG31	NC			
6	IO_L21N_6/VREF_6	AG32	NC			
6	IO_L22P_6	AF29	NC			
6	IO_L22N_6	AF30	NC			
6	IO_L23P_6	AE27	NC			
6	IO_L23N_6	AE28	NC			
6	IO_L24P_6	AH33	NC			
6	IO_L24N_6	AH34	NC			
6	IO_L31P_6	AF31				
6	IO_L31N_6	AF32				
6	IO_L32P_6	AC25				
6	IO_L32N_6	AC26				
6	IO_L33P_6	AG33				
6	IO_L33N_6/VREF_6	AG34				

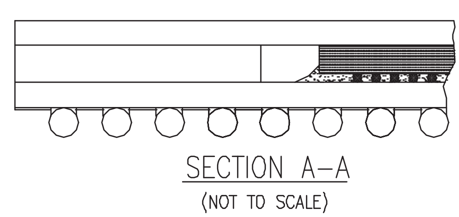
Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
7	VCCO_7	T23				
7	VCCO_7	U23				
N/A	CCLK	AE9				
N/A	PROG_B	J26				
N/A	DONE	AE10				
N/A	M0	AF26				
N/A	M1	AE26				
N/A	M2	AE25				
N/A	TCK	J9				
N/A	TDI	H28				
N/A	TDO	H7				
N/A	TMS	K10				
N/A	PWRDWN_B	AF9				
N/A	HSWAP_EN	K25				
N/A	RSVD	G8				
N/A	VBATT	K9				
N/A	DXP	K26				
N/A	DXN	G27				
N/A	AVCCAUXTX2	B32	NC	NC		
N/A	VTTXPAD2	B33	NC	NC		
N/A	TXNPAD2	A33	NC	NC		
N/A	TXPPAD2	A32	NC	NC		
N/A	GNDA2	C30	NC	NC		
N/A	RXPPAD2	A31	NC	NC		
N/A	RXNPAD2	A30	NC	NC		
N/A	VTRXPAD2	B31	NC	NC		
N/A	AVCCAUXRX2	B30	NC	NC		
N/A	AVCCAUXTX4	B28				
N/A	VTTXPAD4	B29				
N/A	TXNPAD4	A29				
N/A	TXPPAD4	A28				
N/A	GNDA4	C27				
N/A	RXPPAD4	A27				
N/A	RXNPAD4	A26				
N/A	VTRXPAD4	B27				
N/A	AVCCAUXRX4	B26				
N/A	AVCCAUXTX5	B24	NC	NC	NC	

FF1152 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch)



SYMBOL	MILLIMETERS MIN.	NOM.	MAX.	NOTE
A	—	3.20	3.40	
A_1	0.40	0.50	0.60	
A_2	—	—	2.80	
D/E	35.00 BASIC			
D_1/E_1	33.00 REF			
e	1.00 BASIC			
øb	0.50	0.60	0.70	
aaa	—	—	0.20	
ccc	—	—	0.35	
ddd	—	—	0.30	
eee	—	—	0.10	
M	34			2



NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M–1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS–034–AAR–1 (DEPOPULATED)

Figure 6: **FF1152 Flip-Chip Fine-Pitch BGA Package Specifications**

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
N/A	GND	AM39		
N/A	GND	AH39		
N/A	GND	AD39		
N/A	GND	T39		
N/A	GND	M39		
N/A	GND	H39		
N/A	GND	C39		
N/A	GND	AV38		
N/A	GND	AU38		
N/A	GND	AA38		
N/A	GND	W38		
N/A	GND	C38		

Notes:
1. See Table 4 for an explanation of the signals available on this pin.

FF1704 Flip-Chip Fine-Pitch BGA Package

As shown in Table 13, XC2VP70 and XC2VP100 Virtex-II Pro devices are available in the FF1704 flip-chip fine-pitch BGA package. Following this table are the FF1704 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch).

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
0	IO_L01N_0/VRP_0		G34		
0	IO_L01P_0/VRN_0		H34		
0	IO_L02N_0		F34		
0	IO_L02P_0		E34		
0	IO_L03N_0		C34		
0	IO_L03P_0/VREF_0		D34		
0	IO_L05_0/No_Pair		K32		
0	IO_L06N_0		H33		
0	IO_L06P_0		J33		
0	IO_L07N_0		F33		
0	IO_L07P_0		G33		
0	IO_L08N_0		E33		
0	IO_L08P_0		D33		
0	IO_L09N_0		H32		
0	IO_L09P_0/VREF_0		J32		
0	IO_L19N_0		E32		
0	IO_L19P_0		F32		
0	IO_L20N_0		C33		
0	IO_L20P_0		C32		
0	IO_L21N_0		K31		
0	IO_L21P_0		L31		
0	IO_L25N_0		H31		
0	IO_L25P_0		J31		
0	IO_L26N_0		G31		
0	IO_L26P_0		F31		
0	IO_L27N_0		D31		
0	IO_L27P_0/VREF_0		E31		
0	IO_L28N_0		L30		
0	IO_L28P_0		M30		
0	IO_L29N_0		J30		
0	IO_L29P_0		K30		
0	IO_L30N_0		G30		
0	IO_L30P_0		H30		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
2	IO_L26P_2		N12		
2	IO_L27N_2		P9		
2	IO_L27P_2		P10		
2	IO_L28N_2/VREF_2		P7		
2	IO_L28P_2		P8		
2	IO_L29N_2		P11		
2	IO_L29P_2		P12		
2	IO_L30N_2		P5		
2	IO_L30P_2		P6		
2	IO_L31N_2		P1		
2	IO_L31P_2		P2		
2	IO_L32N_2		R9		
2	IO_L32P_2		R10		
2	IO_L33N_2		R5		
2	IO_L33P_2		R6		
2	IO_L34N_2/VREF_2		P3		
2	IO_L34P_2		R3		
2	IO_L35N_2		R1		
2	IO_L35P_2		R2		
2	IO_L36N_2		R11		
2	IO_L36P_2		R12		
2	IO_L37N_2		T6		
2	IO_L37P_2		T7		
2	IO_L38N_2		T8		
2	IO_L38P_2		R8		
2	IO_L39N_2		T4		
2	IO_L39P_2		T5		
2	IO_L40N_2/VREF_2		T2		
2	IO_L40P_2		T3		
2	IO_L41N_2		T10		
2	IO_L41P_2		T11		
2	IO_L42N_2		U7		
2	IO_L42P_2		U8		
2	IO_L43N_2		U5		
2	IO_L43P_2		U6		
2	IO_L44N_2		U9		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
3	IO_L17N_3		AL9		
3	IO_L17P_3		AL10		
3	IO_L16N_3		AM1		
3	IO_L16P_3		AM2		
3	IO_L15N_3/VREF_3		AM3		
3	IO_L15P_3		AN3		
3	IO_L14N_3		AM8		
3	IO_L14P_3		AM9		
3	IO_L13N_3		AM4		
3	IO_L13P_3		AM5		
3	IO_L12N_3		AM6		
3	IO_L12P_3		AM7		
3	IO_L11N_3		AN9		
3	IO_L11P_3		AM10		
3	IO_L10N_3		AN1		
3	IO_L10P_3		AN2		
3	IO_L09N_3/VREF_3		AN5		
3	IO_L09P_3		AN6		
3	IO_L08N_3		AN7		
3	IO_L08P_3		AN8		
3	IO_L07N_3		AP1		
3	IO_L07P_3		AP2		
3	IO_L84N_3		AP4		
3	IO_L84P_3		AP5		
3	IO_L83N_3		AR7		
3	IO_L83P_3		AP8		
3	IO_L82N_3		AP6		
3	IO_L82P_3		AP7		
3	IO_L81N_3/VREF_3		AR2		
3	IO_L81P_3		AR3		
3	IO_L80N_3		AT5		
3	IO_L80P_3		AR6		
3	IO_L79N_3		AR4		
3	IO_L79P_3		AR5		
3	IO_L78N_3		AT1		
3	IO_L78P_3		AT2		

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
N/A	GND	AF1	
N/A	GND	AC1	
N/A	GND	Y1	
N/A	GND	U1	
N/A	GND	N1	
N/A	GND	J1	
N/A	GND	E1	

Notes:

1. See Table 4 for an explanation of the signals available on this pin.